# LDS-1470-DFB-2.5G-15/45

## OVERVIEW
LDS-1470-DFB-2.5G-15/45 is the MQW laser diode coupled to an optical fiber and packaged into a hermetic case. The special feature of the LDS technology is the increased thermal stability of optical power.

## MAIN FEATURES
- Wavelength: 1470 nm
- Cavity type: DFB
- Linewidth: <500 kHz
- Data rate up to 2.5 Gbps
- Optical power: up to 15 mW in CW mode, up to 45 mW in SM fiber G.657.A1
- Package types: coaxial, coaxial with bracket, 14 pins DIL
- Built-in monitor photodiode

## APPLICATIONS
- Optical fiber communication systems with data rate up to 2.5 Gbps
- Laser systems

## ORDERING INFORMATION

<table>
<thead>
<tr>
<th>Case type</th>
<th>Fiber type</th>
<th>Connector type</th>
<th>Test measurements</th>
<th>Fiber length</th>
</tr>
</thead>
<tbody>
<tr>
<td>U: compact coaxial (pulse mode only)</td>
<td>SM1: SM, G.657.A1, furcation tubing Ø0.9 mm</td>
<td>FU: FC/UPC</td>
<td>CW: CW mode (electro-optical parameters at T=25+/-5 C and spectrum)</td>
<td>0.5: 500+/-50 mm</td>
</tr>
<tr>
<td>B: compact coaxial with double-sided bracket</td>
<td>SM3: SM, G.657.B3, furcation tubing Ø0.9 mm</td>
<td>FA: FC/APC</td>
<td>P: pulse mode (10 μs; duty cycle = 1%)</td>
<td>1.0: 1000+/-100 mm</td>
</tr>
<tr>
<td>T: 14 pins DIL with thermal stabilization (TEC and thermistor)</td>
<td>SMP13: PM, Fujikura SM13, PANDA type, furcation tubing Ø0.9 mm</td>
<td>N: no connector</td>
<td>CWP: both CW and pulse modes</td>
<td>Other length on request</td>
</tr>
<tr>
<td>E: 14 pins DIL with thermal stabilization (TEC and thermistor)</td>
<td>Other type on request</td>
<td>Other type: on request</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Other type on request
# LDS-1470-DFB-2.5G-15/45

## ABSOLUTE MAXIMUM RATINGS

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Value</th>
<th>Unit</th>
<th>Conditions</th>
</tr>
</thead>
<tbody>
<tr>
<td>Laser diode forward current</td>
<td>I_{FL}</td>
<td>120  mA</td>
<td>CW</td>
</tr>
<tr>
<td>Laser diode reverse voltage</td>
<td>V_{RL}</td>
<td>2    V</td>
<td></td>
</tr>
<tr>
<td>Photodiode reverse voltage</td>
<td>V_{RP}</td>
<td>20   V</td>
<td></td>
</tr>
<tr>
<td>Photodiode forward current</td>
<td>I_{FP}</td>
<td>2    mA</td>
<td></td>
</tr>
<tr>
<td>Operating temperature</td>
<td>T_{OP}</td>
<td>-40 - +85 °C</td>
<td>Package U, B</td>
</tr>
<tr>
<td>Storage temperature</td>
<td>T_{stg}</td>
<td>-50 - +85 °C</td>
<td>Package T, E</td>
</tr>
<tr>
<td>Soldering temperature</td>
<td>T_{sold}</td>
<td>260 °C</td>
<td>Max. 10 seconds</td>
</tr>
</tbody>
</table>

## ELECTRICAL-OPTICAL CHARACTERISTICS (T = 25 °C)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>Unit</th>
<th>Conditions</th>
</tr>
</thead>
<tbody>
<tr>
<td>Wavelength</td>
<td>1467</td>
<td>1470</td>
<td>1473</td>
<td>nm</td>
<td>CW, P = 15 mW</td>
</tr>
<tr>
<td>Spectral width</td>
<td>0.09</td>
<td>nm</td>
<td></td>
<td></td>
<td>CW, P = 15 mW, -20 dB, OSA</td>
</tr>
<tr>
<td>Spectral width</td>
<td>500  kHz</td>
<td></td>
<td></td>
<td></td>
<td>CW, P = 15 mW, delayed self-heterodyne method</td>
</tr>
<tr>
<td>Wavelength-temperature coeff.</td>
<td>0.1  nm/°C</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Side-mode suppression ratio</td>
<td>40</td>
<td>55</td>
<td></td>
<td>dB</td>
<td>CW, P = 15 mW</td>
</tr>
<tr>
<td>Threshold current</td>
<td>I_{th}</td>
<td>8</td>
<td>12</td>
<td>mA</td>
<td>CW</td>
</tr>
<tr>
<td>Operating voltage</td>
<td>V_{op}</td>
<td>1.4</td>
<td>1.8</td>
<td>V</td>
<td>CW, P = 15 mW</td>
</tr>
<tr>
<td>Tracking error</td>
<td>E_{r}</td>
<td>0.15</td>
<td>0.30</td>
<td>dB</td>
<td>CW, P = 3 mW; T = -40 ÷ +80 °C</td>
</tr>
<tr>
<td>Pulse optical power</td>
<td>P_{p}</td>
<td>40</td>
<td>45</td>
<td>mW</td>
<td>Pulse, Iop = 450 mA</td>
</tr>
<tr>
<td>Rise and fall times</td>
<td>t_r, t_f</td>
<td>80</td>
<td>120</td>
<td>ps</td>
<td>20%-80%, package U, B</td>
</tr>
<tr>
<td>Resonance frequency</td>
<td>f_r</td>
<td>6.0</td>
<td>GHz</td>
<td></td>
<td>2.5Gbps, I_{mod} = 40mA, I_{bias} = I_{th} + 2mA</td>
</tr>
<tr>
<td>Monitoring output current (PD)</td>
<td>I_m</td>
<td>1.0</td>
<td>1.7</td>
<td>5.0</td>
<td>mA</td>
</tr>
<tr>
<td>Capacitance (PD)</td>
<td>C_t</td>
<td>10</td>
<td>20</td>
<td>pF</td>
<td>V_{rd} = 5V, f = 1 MHz</td>
</tr>
<tr>
<td>Dark current (PD)</td>
<td>I_d</td>
<td>100  nA</td>
<td></td>
<td></td>
<td>V_{rd} = 5V</td>
</tr>
<tr>
<td>Polarization extinction ratio</td>
<td>PER</td>
<td>20</td>
<td>dB</td>
<td></td>
<td>CW, SMP13</td>
</tr>
</tbody>
</table>

Pulse mode: pulse duration 10 μs; duty cycle = 1%
Tracking error \( E_{r} = \max\{10 \log [P(T)/P(25°C)]\} \), \( I_{m} \) = const, \( T = T_{\min} \pm T_{\max} \)
**LASER DIODE**

**LDS-1470-DFB-2.5G-15/45**

**PACKAGE U**

**SIDE VIEW**

**BACK VIEW**

**PINOUT #2**

Connector FC/UPC, FC/APC, no connector, or by request

Fiber length 500+/−50, 1000+/−100, or by request

**PACKAGE B**

**SIDE VIEW**

**BACK VIEW**

**PINOUT #2**

Connector FC/UPC, FC/APC, no connector, or by request

Fiber length 500+/−50, 1000+/−100, or by request

**PACKAGE T**

**FRONT VIEW**

**BOTTOM VIEW**

**PINOUT #2, #3**

1. TEC Anode
2. 
3. 
4. 
5. LD Anode
6. 
7. PD Cathode, LD Anode
8. PD Anode
9. LD Cathode
10. LD Anode
11. Thermistor
12. 
13. 
14. TEC Cathode

TEC: I(T) = 0.7A, U(T) = 3.9V, Q(T) = 1.4W,
AC R = 4.7 Ohm, ΔTmax = 72 K
Thermistor:
Rt = 100kΩ EXP(3600/\{1/(T[K]-1/298]) kΩm

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LASER DIODE

LDS-1470-DFB-2.5G-15/45

PACKAGE E

PINOUT #2, #3
1. TEC Anode
2.-
3.-
4.-
5. LD Anode
6.-
7. PD Cathode, LD Anode
8. PD Anode
9. LD Cathode
10. LD Anode
11. Thermistor
12. Thermistor
13.-
14. TEC Cathode

TEC: I_TEC=0.7A, U_TEC=3.9V, Q_TEC=1.4W,
AC R = 4.7 Ohm, B50m= 72 K
Thermistor:
R_T = 10^5*EXP[3600*(1/T[K]-1/298)] kOhm
LDS-1470-DFB-2.5G-15/45

Characteristics, data, materials and structures specified in this datasheet are subject to change without notice. Please refer to the latest specification before use of the products.

Safety and handling cautions
1. Avoid smashing and burning of the module. Avoid storing and using the module in conditions where water, organic solvents or aggressive acids or bases may contact the module or where there is a possibility of exposure to corrosive gases, explosive gases, dust, salinity or other harsh conditions. The module should be disposed as special industrial waste.
2. Exceeding absolute maximum ratings even for a short time can cause permanent damage of the module.
3. The module is sensitive to and can be broken by ESD (static electricity).

Conflict Minerals Policy Statement
LasersCom LLC achieves business objectives and customer needs with social responsibility. We do not support or contribute to the violence and human rights violations associated with the mining of conflict minerals coming from Conflict Regions according to US "Dodd-Frank Act". When possible, our suppliers’ conflict mineral statements are reviewed. We do not directly purchase Conflict Minerals from any source and do not knowingly procure any parts and products containing Conflict Minerals from Conflict Regions.

RoHS Compliance Statement
Restriction of Hazardous Substances (RoHS) directive (Directive 2011/65/EC amended with Directive (EU) 2015/863) is the directive aimed at reducing the harmful environmental impact of waste electrical equipment by restricting the use of known dangerous substances. Based on information received from our supply sources, LasersCom LLC hereby states that the banned substances listed in the RoHS directive are not found in the parts and materials used above the threshold level listed other than exceptions approved by the European Commission.

REACH Compliance Statement
Registration, Evaluation, Authorisation and Restriction of Chemicals (REACH) is a European Union regulation 1907/2006/EC that addresses the production and use of chemical substances, and their potential impacts on human health and the environment. Based on information received from our supply sources, LasersCom LLC hereby states compliance of the parts and materials used in manufacturing to REACH regulation. LasersCom LLC does not manufacture or import any substances or preparations as defined under REACH.